



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-07-08
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacobello	Representative Title	IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HJUF*Z29J43Q	A	Z55A	2015-07-08
Amount	UoM	Unit type	ST ECOPACK Grade	
9.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Alloy 42		

Package Designator	Size	Nbr of instances	Shape	
DSO	2.672X1.57X1.094	2	gull wing	
Comment	Package: SOD 123 2L 1.0mm; MDF valid for 2031-771023-000; STPS0520Z			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HJUF*Z29M3Q						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Silicon die	Other inorganic materials	0.374	mg	supplier	die	Silicon (Si)	7440-21-3		0.351	mg	938503	39000	
Silicon die				supplier	metallization	Aluminum (Al)	7429-90-5		0.017	mg	45455	1889	
Silicon die				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	2674	111	
Silicon die				supplier	metallization	Nickel (Ni)	7440-02-0		0.002	mg	5348	222	
Silicon die				supplier	Passivation	Silicon Oxide	7631-86-9		0.002	mg	5348	222	
Silicon die				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	2674	111	
Leadframe	Other Ferrous alloys, non-stainless ste	2.531	mg	supplier	alloy	Iron (Fe)	7439-89-6		1.417	mg	55958	157444	
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		1.007	mg	397866	111889	
Leadframe				supplier	alloy	Manganese (Mn)	7439-96-5		0.015	mg	5927	1667	
Leadframe				supplier	alloy	Chromium (Cr)	7440-47-3		0.002	mg	790	222	
Leadframe				supplier	alloy	Cobalt (Co)	7440-48-4		0.012	mg	4741	1333	
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		0.003	mg	1185	333	
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.075	mg	29633	8333	
Bonding wires	Precious metals	0.011	mg	supplier	wire	Gold (Au)	7440-57-5		0.011	mg	1000000	1222	
Encapsulation	Other Organic Materials	5.909	mg	supplier	mold compound	SiO2	60676-86-0		5.078	mg	859367	564222	
Encapsulation				supplier	Molding compound	Epoxy Cresol Novolak	29690-82-2		0.291	mg	49247	32333	
Encapsulation				supplier	Molding compound	Phenol Resin	26834-02-6		0.291	mg	49247	32333	
Encapsulation				supplier	Molding compound	Aromatic poly-phosphate	139189-30-3		0.145	mg	24539	16111	
Encapsulation				supplier	Molding compound	Carbon Black	1333-86-4		0.011	mg	1862	1222	
Encapsulation				supplier	Molding compound	Biphenyl epoxy resin	85954-11-6		0.093	mg	15739	10333	
connections coating	Solder	0.175	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.175	mg	1000000	19444	